



# SI1428EDH

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
30	0.045 at V <sub>GS</sub> = 10 V	4	4 nC
	0.049 at V <sub>GS</sub> = 4.5 V	4	
	0.060 at V <sub>GS</sub> = 2.5 V	4	

## FEATURES

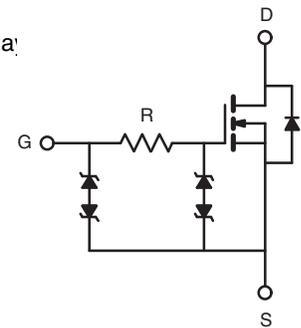
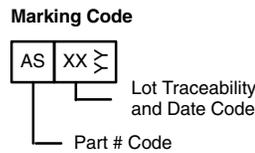
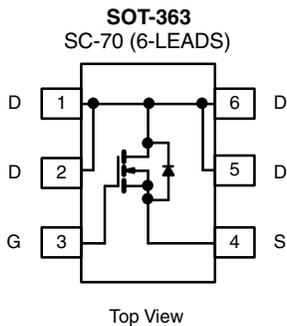
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Typical ESD Protection 2000 V HBM
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS COMPLIANT  
HALOGEN FREE

## APPLICATIONS

- Portable Devices
  - Load Switch
  - Battery Switch
- Load Switch for Motors, Relays



Ordering Information: Si1428EDH-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 12		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	T <sub>C</sub> = 25 °C	A	
		T <sub>C</sub> = 70 °C		
		T <sub>A</sub> = 25 °C		
		T <sub>A</sub> = 70 °C		
Pulsed Drain Current (t = 300 μs)	I <sub>DM</sub>	20		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	W	
		T <sub>A</sub> = 25 °C		
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25 °C		
		T <sub>C</sub> = 70 °C		
		T <sub>A</sub> = 25 °C		
		T <sub>A</sub> = 70 °C		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	R <sub>thJA</sub>	60	80	°C/W	
Maximum Junction-to-Foot (Drain)	R <sub>thJF</sub>	34	45		

**Notes:**

- a. Package limited, T<sub>C</sub> = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 125 °C/W.



SI1428EDH

SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	30			V
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA		23		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	ΔV <sub>GS(th)</sub> /T <sub>J</sub>			- 3.2		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	0.6		1.3	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 4.5 V			± 0.5	μA
		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 12 V			± 25	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	
		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5 V, V <sub>GS</sub> = 4.5 V	15			A
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.7 A		0.036	0.045	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3.6 A		0.040	0.049	
		V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 1.5 A		0.048	0.060	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3.7 A		17		S
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.7 A		8.8	13.5	nC
				4	6	
				0.9		
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4.7 A		1.1		
Gate-Drain Charge	Q <sub>gd</sub>					
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2	4	kΩ
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, R <sub>L</sub> = 4.1 Ω I <sub>D</sub> ≈ 3.7 A, V <sub>GEN</sub> = 4.5 V, R <sub>g</sub> = 1 Ω		0.29	0.58	μs
Rise Time	t <sub>r</sub>			0.4	0.8	
Turn-Off DelayTime	t <sub>d(off)</sub>			1.9	3.8	
Fall Time	t <sub>f</sub>			0.75	1.5	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, R <sub>L</sub> = 4.1 Ω I <sub>D</sub> ≈ 3.7 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 1 Ω		0.1	0.2	
Rise Time	t <sub>r</sub>			0.15	0.3	
Turn-Off DelayTime	t <sub>d(off)</sub>			3	6	
Fall Time	t <sub>f</sub>			0.75	1.5	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.3	A
Pulse Diode Forward Current	I <sub>SM</sub>				20	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 3.7 A, V <sub>GS</sub> = 0 V		0.85	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3.7 A, dI/dt = 100 A/μs, T <sub>J</sub> = 25 °C		12	25	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			5	10	nC
Reverse Recovery Fall Time	t <sub>a</sub>			6.5		ns
Reverse Recovery Rise Time	t <sub>b</sub>			5.5		

**Notes:**

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- b. Guaranteed by design, not subject to production testing.